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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	AVR
Core Size	8/16-Bit
Speed	32MHz
Connectivity	I ² C, IrDA, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	50
Program Memory Size	128KB (64K x 16)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 3.6V
Data Converters	A/D 16x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atxmega128a3u-anr

- Programming and debug interfaces
 - JTAG (IEEE 1149.1 compliant) interface, including boundary scan
 - PDI (program and debug interface)
- I/O and packages
 - 50 Programmable I/O pins
 - 64-lead TQFP
 - 64-pad QFN
- Operating voltage
 - 1.6 – 3.6V
- Operating frequency
 - 0 – 12MHz from 1.6V
 - 0 – 32MHz from 2.7V

36. Electrical Characteristics

All typical values are measured at $T = 25^{\circ}\text{C}$ unless other temperature condition is given. All minimum and maximum values are valid across operating temperature and voltage unless other conditions are given.

Note: For devices that are not available yet, preliminary values in this datasheet are based on simulations, and/or characterization of similar AVR XMEGA microcontrollers. After the device is characterized the final values will be available, hence existing values can change. Missing minimum and maximum values will be available after the device is characterized.

36.1 ATxmega64A3U

36.1.1 Absolute Maximum Ratings

Stresses beyond those listed in [Table 36-1](#) under may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Table 36-1. Absolute maximum ratings.

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
V_{CC}	Power Supply Voltage		-0.3		4	V
$I_{V_{\text{CC}}}$	Current into a V_{CC} pin				200	mA
I_{GND}	Current out of a Gnd pin				200	mA
V_{PIN}	Pin voltage with respect to Gnd and V_{CC}		-0.5		$V_{\text{CC}}+0.5$	V
I_{PIN}	I/O pin sink/source current		-25		25	mA
T_A	Storage temperature		-65		150	°C
T_j	Junction temperature				150	°C

36.1.2 General Operating Ratings

The device must operate within the ratings listed in [Table 36-2](#) in order for all other electrical characteristics and typical characteristics of the device to be valid.

Table 36-2. General operating conditions.

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
V_{CC}	Power Supply Voltage		1.60		3.6	V
$A V_{\text{CC}}$	Analog Supply Voltage		1.60		3.6	V
T_A	Temperature range	85 °C	-40		85	°C
		105 °C	-40		105	
T_j	Junction temperature	85°C	-40		105	°C
		105°C	-40		125	

36.1.14.6 External clock characteristics

Figure 36-3. External clock drive waveform

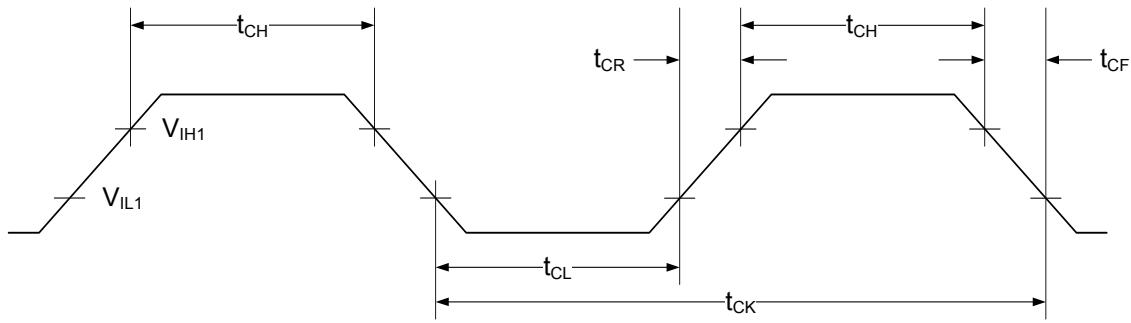


Table 36-27. External clock used as system clock without prescaling.

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
1/t _{CK}	Clock Frequency ⁽¹⁾	V _{CC} = 1.6 - 1.8V	0		12	MHz
		V _{CC} = 2.7 - 3.6V	0		32	
t _{CK}	Clock Period	V _{CC} = 1.6 - 1.8V	83.3			ns
		V _{CC} = 2.7 - 3.6V	31.5			
t _{CH}	Clock High Time	V _{CC} = 1.6 - 1.8V	30.0			ns
		V _{CC} = 2.7 - 3.6V	12.5			
t _{CL}	Clock Low Time	V _{CC} = 1.6 - 1.8V	30.0			ns
		V _{CC} = 2.7 - 3.6V	12.5			
t _{CR}	Rise Time (for maximum frequency)	V _{CC} = 1.6 - 1.8V			10	ns
		V _{CC} = 2.7 - 3.6V			3	
t _{CF}	Fall Time (for maximum frequency)	V _{CC} = 1.6 - 1.8V			10	ns
		V _{CC} = 2.7 - 3.6V			3	
Δt _{CK}	Change in period from one clock cycle to the next				10	%

Note: 1. The maximum frequency vs. supply voltage is linear between 1.8V and 2.7V, and the same applies for all other parameters with supply voltage conditions.

Symbol	Parameter	Condition		Min.	Typ.	Max.	Units
t_{delay}	Propagation delay	mode = HS	$V_{\text{CC}} = 3.0\text{V}, T = 85^{\circ}\text{C}$		90	100	ns
			$V_{\text{CC}} = 1.6\text{V} - 3.6\text{V}$		95		
		mode = LP			200	500	
	64-Level Voltage Scaler	Integral non-linearity (INL)			0.5	1.0	lsb

36.2.9 Bandgap and Internal 1.0V Reference Characteristics

Table 36-48. Bandgap and Internal 1.0V reference characteristics.

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
	Startup time	As reference for ADC or DAC		$1 \text{ CLK}_{\text{PER}} + 2.5\mu\text{s}$		μs
		As input voltage to ADC and AC		1.5		
	Bandgap voltage			1.1		V
INT1V	Internal 1.00V reference	$T = 85^{\circ}\text{C}$, after calibration	0.99	1	1.01	
	Variation over voltage and temperature	Relative to $T = 85^{\circ}\text{C}$, $V_{\text{CC}} = 3.0\text{V}$		± 1.0		%

36.2.10 Brownout Detection Characteristics

Table 36-49. Brownout detection characteristics.

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
V_{BOT}	BOD level 0 falling V_{CC}		1.60	1.62	1.72	V
	BOD level 1 falling V_{CC}			1.8		
	BOD level 2 falling V_{CC}			2.0		
	BOD level 3 falling V_{CC}			2.2		
	BOD level 4 falling V_{CC}			2.4		
	BOD level 5 falling V_{CC}			2.6		
	BOD level 6 falling V_{CC}			2.8		
	BOD level 7 falling V_{CC}			3.0		
t_{BOD}	Detection time	Continuous mode		0.4		μs
		Sampled mode		1000		
V_{HYST}	Hysteresis			1.6		%

36.3.6 ADC characteristics

Table 36-72. Power supply, reference and input range.

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
V_{CC}	Analog supply voltage		$V_{CC} - 0.3$		$V_{CC} + 0.3$	V
V_{REF}	Reference voltage		1		$V_{CC} - 0.6$	V
R_{in}	Input resistance	Switched		4.0		kΩ
C_{sample}	Input capacitance	Switched		4.4		pF
R_{AREF}	Reference input resistance	(leakage only)		>10		MΩ
C_{AREF}	Reference input capacitance	Static load		7		pF
V_{IN}	Input range		-0.1		$V_{CC} + 0.1$	V
	Conversion range	Differential mode, $V_{INP} - V_{INN}$	$-V_{REF}$		V_{REF}	V
V_{IN}	Conversion range	Single ended unsigned mode, V_{INP}	$-\Delta V$		$V_{REF} - \Delta V$	V
ΔV	Fixed offset voltage			190		LSB

Table 36-73. Clock and timing.

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
Clk_{ADC}	ADC Clock frequency	Maximum is 1/4 of Peripheral clock frequency	100		2000	kHz
		Measuring internal signals	100		125	
f_{ADC}	Sample rate	Current limitation (CURRLIMIT) off	100		2000	ksps
		CURRLIMIT = LOW	100		1500	
		CURRLIMIT = MEDIUM	100		1000	
		CURRLIMIT = HIGH	100		500	
	Sampling Time	1/2 Clk_{ADC} cycle	0.25		5	μs
	Conversion time (latency)	(RES+2)/2+(GAIN != 0) RES (Resolution) = 8 or 12	5		8	Clk_{ADC} cycles
	Start-up time	ADC clock cycles		12	24	Clk_{ADC} cycles
	ADC settling time	After changing reference or input mode		7	7	Clk_{ADC} cycles
		After ADC flush		1	1	

Table 36-106. Accuracy characteristics.

Symbol	Parameter	Condition ⁽²⁾		Min.	Typ.	Max.	Units
RES	Resolution	Programmable to 8 or 12 bit		8	12	12	Bits
INL ⁽¹⁾	Integral non-linearity	500ksps	$V_{CC}-1.0V < V_{REF} < V_{CC}-0.6V$		± 1.2	± 2	lsb
			All V_{REF}		± 1.5	± 3	
		2000ksps	$V_{CC}-1.0V < V_{REF} < V_{CC}-0.6V$		± 1.0	± 2	
			All V_{REF}		± 1.5	± 3	
DNL ⁽¹⁾	Differential non-linearity	guaranteed monotonic			$<\pm 0.8$	$<\pm 1$	lsb
	Offset Error				-1		mV
		Temperature drift			<0.01		mV/K
		Operating voltage drift			<0.6		mV/V
	Gain Error	Differential mode	External reference		-1		mV
			$AV_{CC}/1.6$		10		
			$AV_{CC}/2.0$		8		
			Bandgap		± 5		
		Temperature drift			<0.02		mV/K
		Operating voltage drift			<0.5		mV/V
	Noise	Differential mode, shorted input 2msps, $V_{CC} = 3.6V$, $Clk_{PER} = 16MHz$			0.4		mV rms

Notes:

1. Maximum numbers are based on characterisation and not tested in production, and valid for 5% to 95% input voltage range.
2. Unless otherwise noted all linearity, offset and gain error numbers are valid under the condition that external V_{REF} is used.

Table 36-107. Gain stage characteristics.

Symbol	Parameter	Condition		Min.	Typ.	Max.	Units
R_{in}	Input resistance	Switched in normal mode			4.0		k Ω
C_{sample}	Input capacitance	Switched in normal mode			4.4		pF
	Signal range	Gain stage output		0		$V_{CC} - 0.6$	V
	Propagation delay	ADC conversion rate			1		Clk_{ADC} cycles
	Sample rate	Same as ADC		100		1000	kHz
INL ⁽¹⁾	Integral Non-Linearity	500ksps	All gain settings		± 1.5	± 4	lsb
	Gain Error	1x gain, normal mode			-0.8		%
		8x gain, normal mode			-2.5		
		64x gain, normal mode			-3.5		

Table 36-110. Accuracy characteristics.

Symbol	Parameter	Condition		Min.	Typ.	Max.	Units
RES	Input Resolution					12	Bits
INL ⁽¹⁾	Integral non-linearity	$V_{REF} = \text{Ext } 1.0V$	$V_{CC} = 1.6V$		± 2.0	± 3	lsb
			$V_{CC} = 3.6V$		± 1.5	± 2.5	
		$V_{REF} = AV_{CC}$	$V_{CC} = 1.6V$		± 2.0	± 4	
			$V_{CC} = 3.6V$		± 1.5	± 4	
		$V_{REF} = INT1V$	$V_{CC} = 1.6V$		± 5.0		
			$V_{CC} = 3.6V$		± 5.0		
DNL ⁽¹⁾	Differential non-linearity	$V_{REF} = \text{Ext } 1.0V$	$V_{CC} = 1.6V$		± 1.5	3	lsb
			$V_{CC} = 3.6V$		± 0.6	1.5	
		$V_{REF} = AV_{CC}$	$V_{CC} = 1.6V$		± 1.0	3.5	
			$V_{CC} = 3.6V$		± 0.6	1.5	
		$V_{REF} = INT1V$	$V_{CC} = 1.6V$		± 4.5		
			$V_{CC} = 3.6V$		± 4.5		
	Gain error	After calibration			<4		lsb
	Gain calibration step size				4		lsb
	Gain calibration drift	$V_{REF} = \text{Ext } 1.0V$			<0.2		mV/K
	Offset error	After calibration			<1		lsb
	Offset calibration step size				1		

Note: 1. Maximum numbers are based on characterisation and not tested in production, and valid for 5% to 95% output voltage range.

36.4.8 Analog Comparator Characteristics

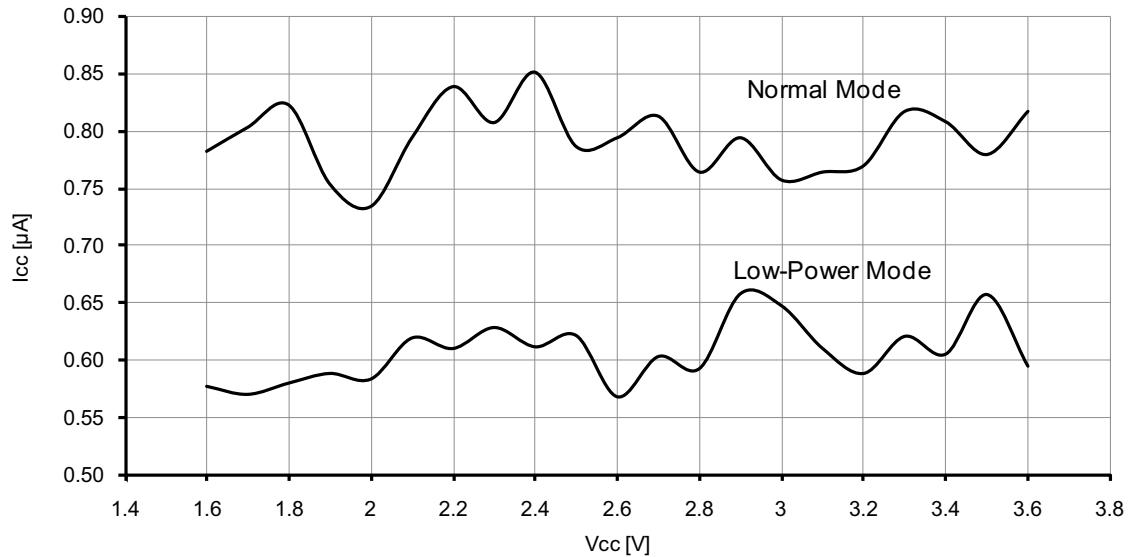
Table 36-111. Analog Comparator characteristics.

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
V_{off}	Input Offset Voltage			$<\pm 10$		mV
I_{lk}	Input Leakage Current			<1		nA
	Input voltage range		-0.1		AV_{CC}	V
	AC startup time			100		μs
V_{hys1}	Hysteresis, None			0		mV
V_{hys2}	Hysteresis, Small	mode = High Speed (HS)		13		mV
		mode = Low Power (LP)		30		
V_{hys3}	Hysteresis, Large	mode = HS		30		mV
		mode = LP		60		

37.1.1.4 Power-save mode supply current

Figure 37-17. Power-save mode supply current vs. V_{CC} .

Real Time Counter enabled and running from 1.024kHz output of 32.768kHz TOSC.
RTC from 1kHz output of 32.768kHz TOSC



37.1.1.5 Standby mode supply current

Figure 37-18. Standby supply current vs. V_{CC} .

Standby, $f_{SYS} = 1MHz$.

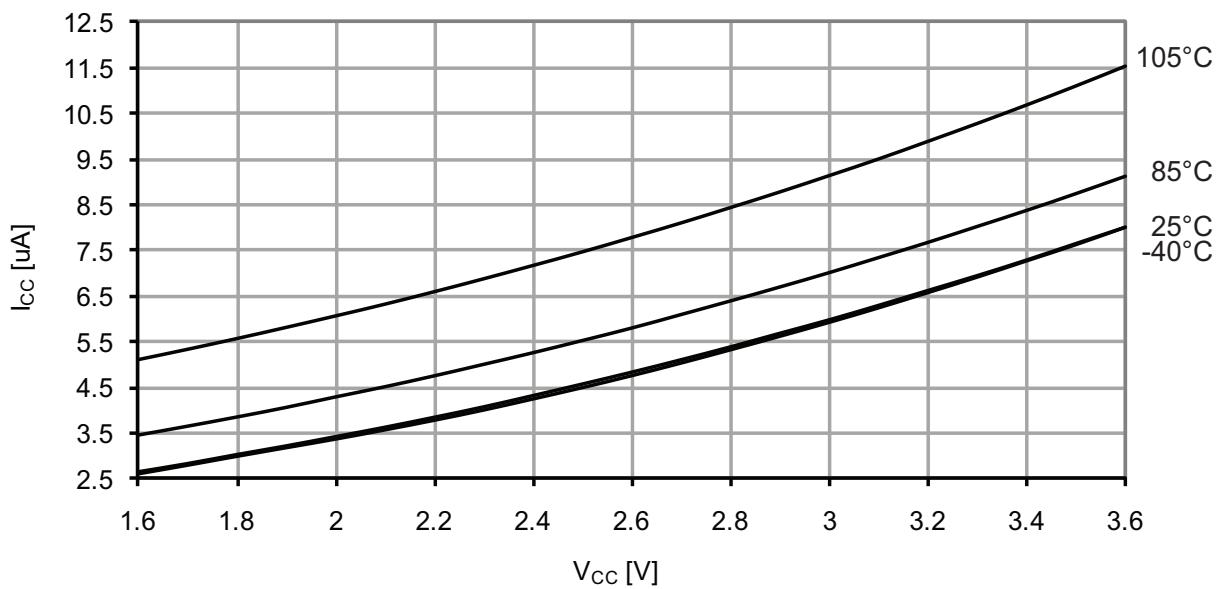


Figure 37-49. DNL error vs. V_{REF} .
 $T = 25^\circ\text{C}$, $V_{CC} = 3.6\text{V}$.

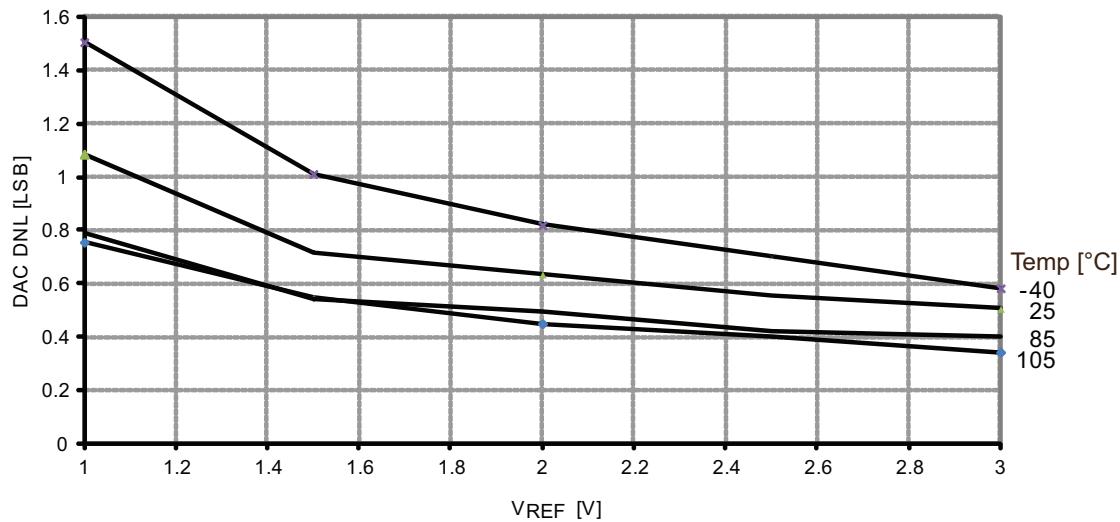


Figure 37-50. DAC noise vs. temperature.
 $V_{CC} = 3.3\text{V}$, $V_{REF} = 2.0\text{V}$.

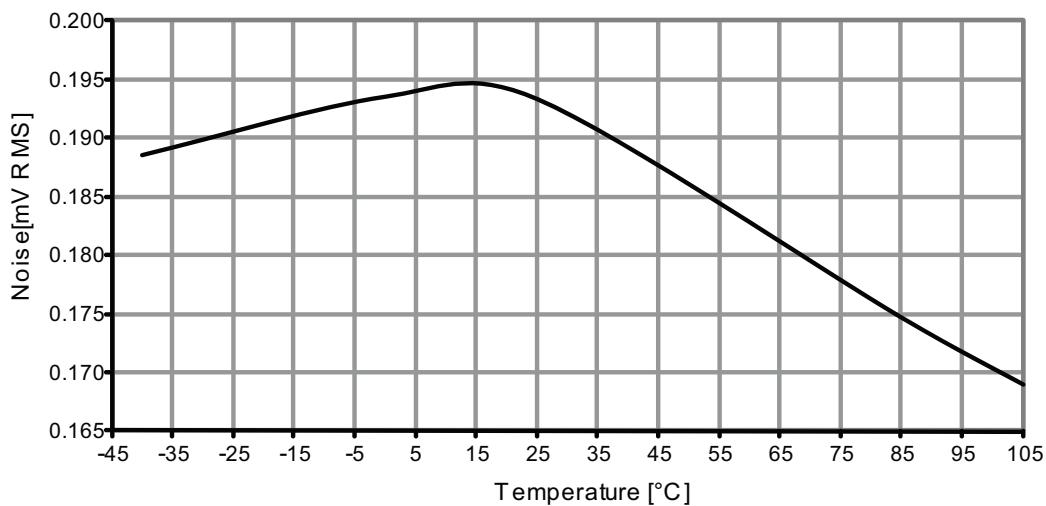


Figure 37-55. Analog comparator current source vs. calibration value.
 Temperature = 25°C.

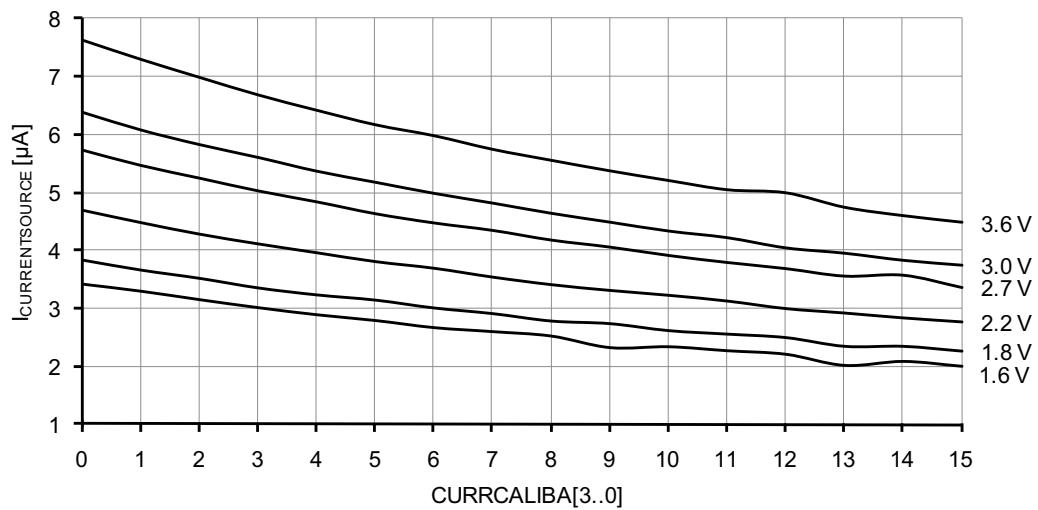
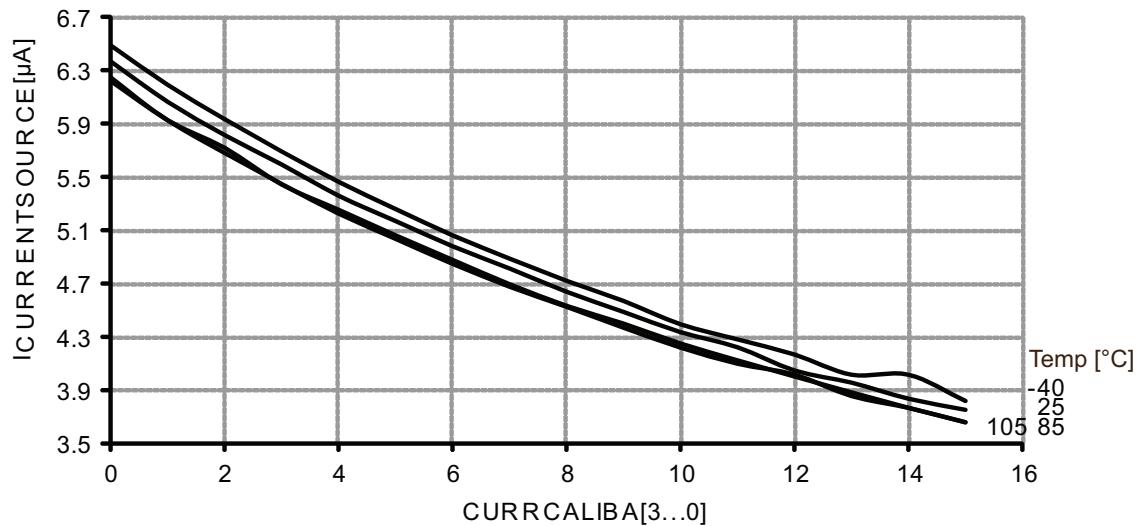


Figure 37-56. Analog comparator current source vs. calibration value.
 $V_{CC} = 3.0V$.



37.1.9 Power-on Reset Characteristics

Figure 37-67. Power-on reset current consumption vs. V_{CC} .
BOD level = 3.0V, enabled in continuous mode.

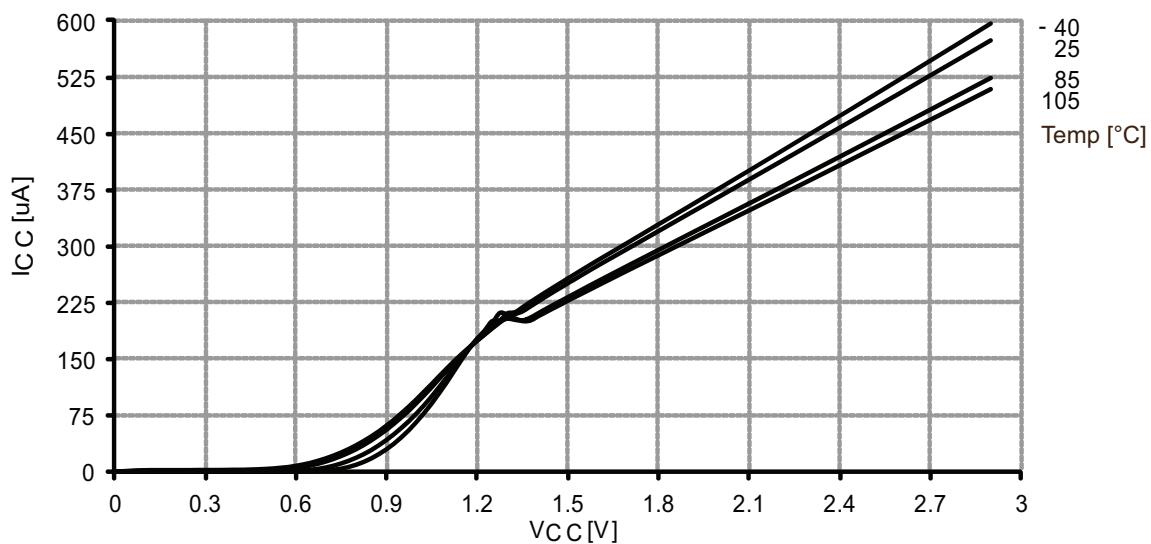


Figure 37-86. Active mode supply current vs. V_{CC} .

$f_{SYS} = 32.768\text{kHz}$ internal oscillator.

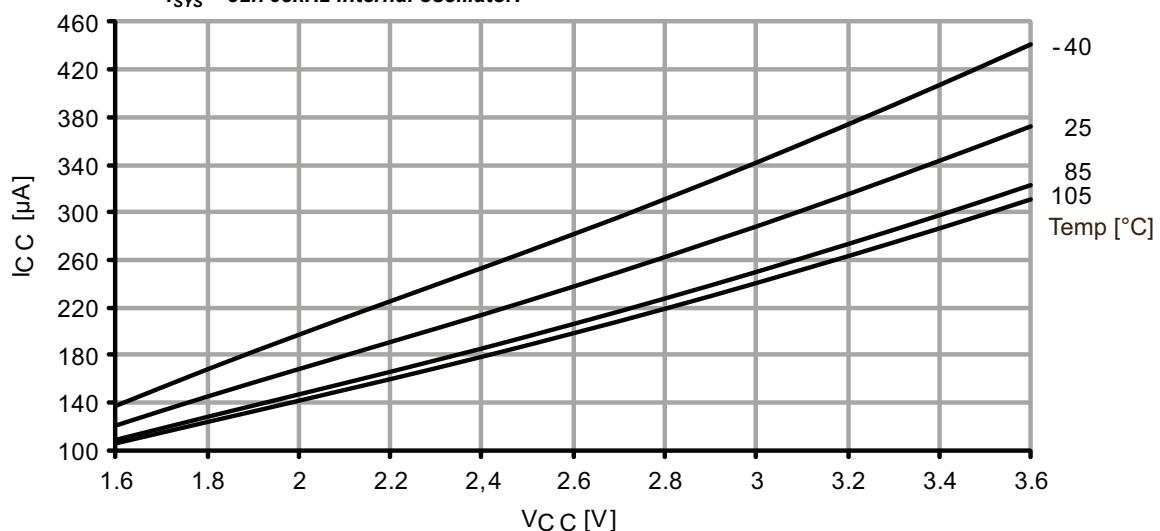
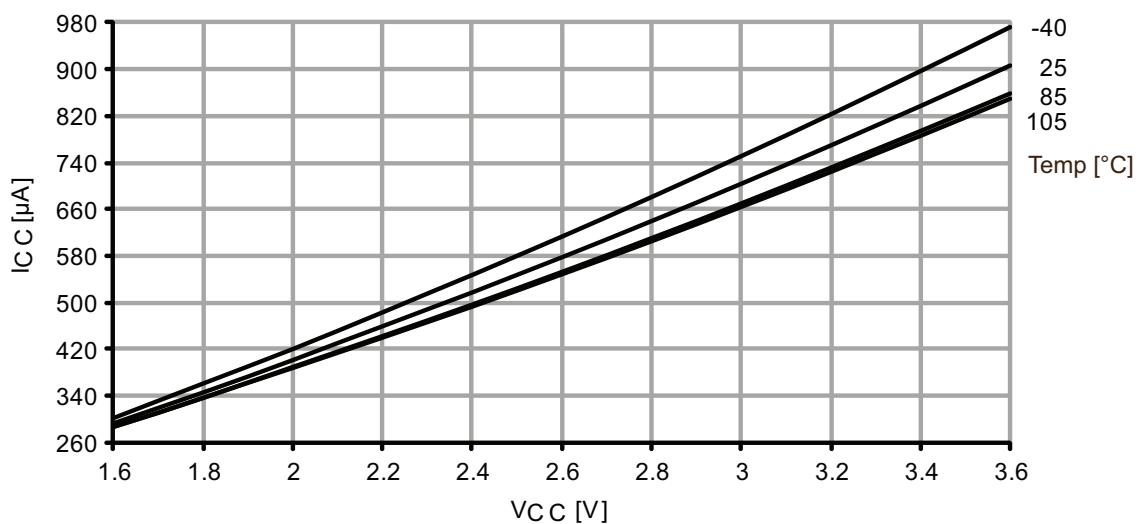


Figure 37-87. Active mode supply current vs. V_{CC} .

$f_{SYS} = 1\text{MHz}$ external clock.



37.2.1.3 Power-down mode supply current

Figure 37-98. Power-down mode supply current vs. V_{CC} .

All functions disabled.

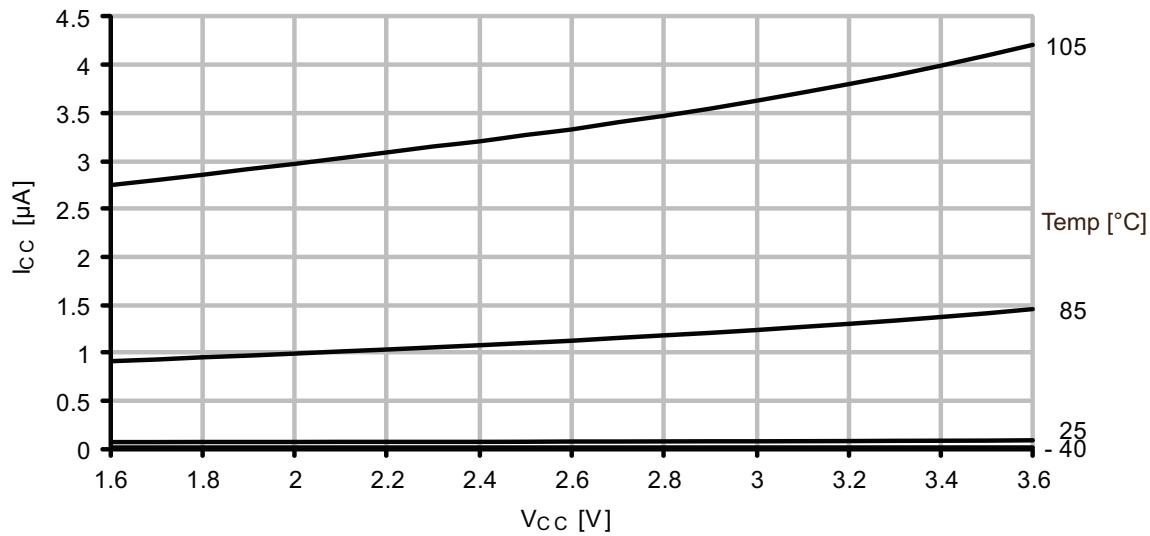


Figure 37-99. Power-down mode supply current vs. V_{CC} .

Watchdog and sampled BOD enabled.

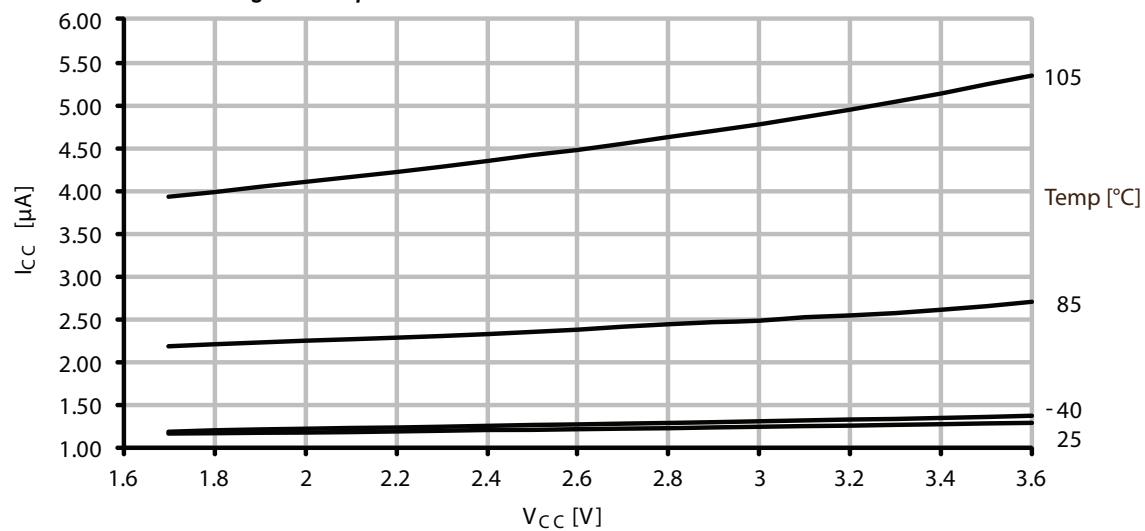
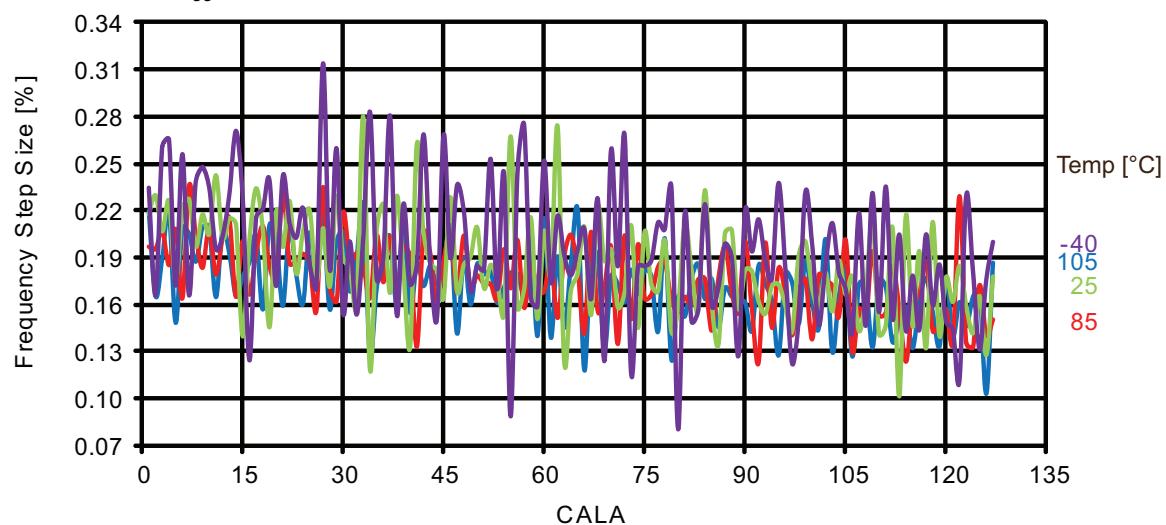


Figure 37-163. 48MHz internal oscillator CALA calibration step size.

$V_{CC} = 3.0V$.



37.2.11 Two-Wire Interface characteristics

Figure 37-164. SDA hold time vs. Vcc.

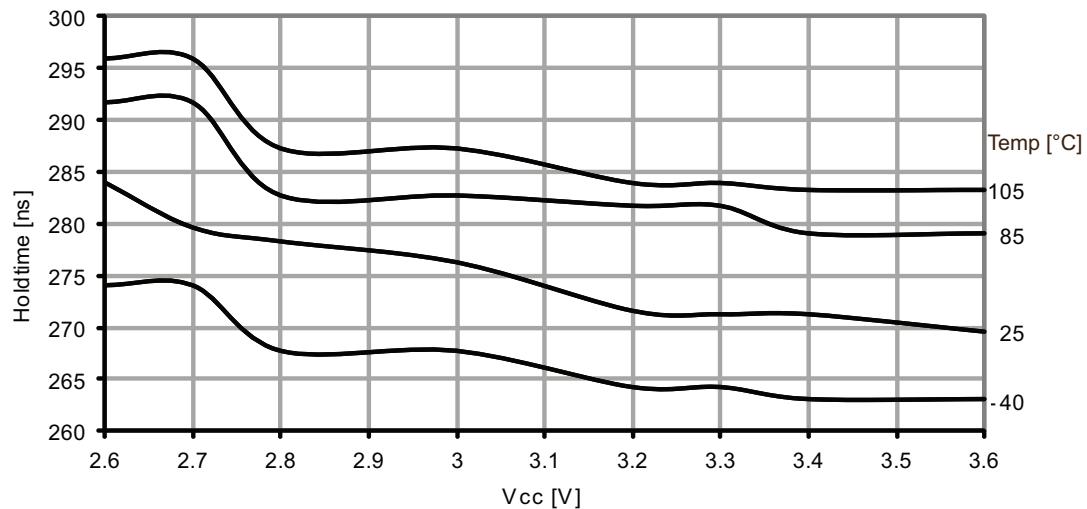


Figure 37-199. I/O pin input threshold voltage vs. V_{CC} .

V_{IL} I/O pin read as “0”.

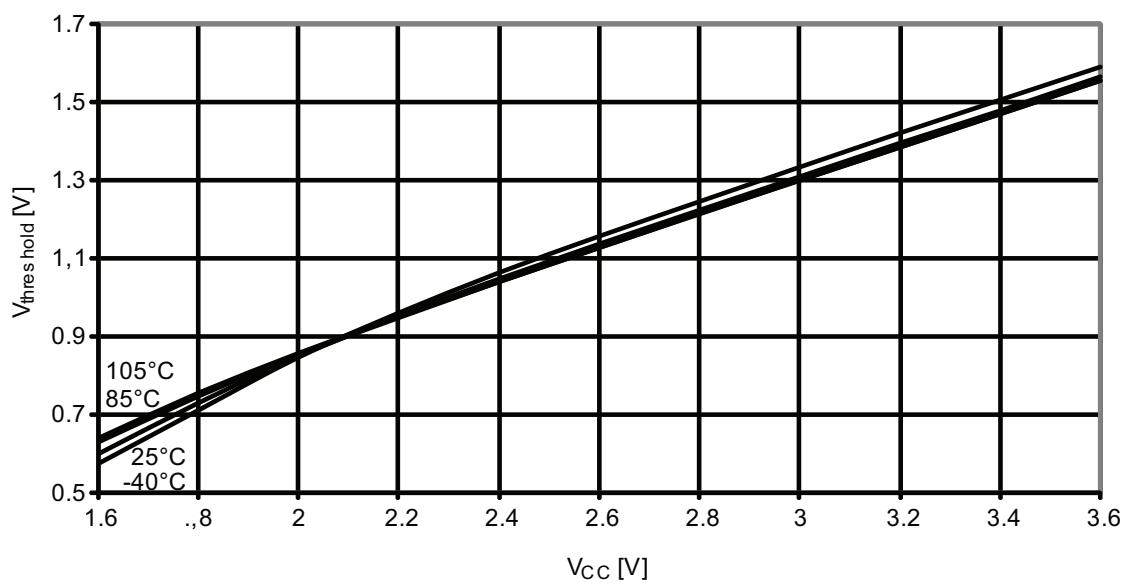


Figure 37-200. I/O pin input hysteresis vs. V_{CC} .

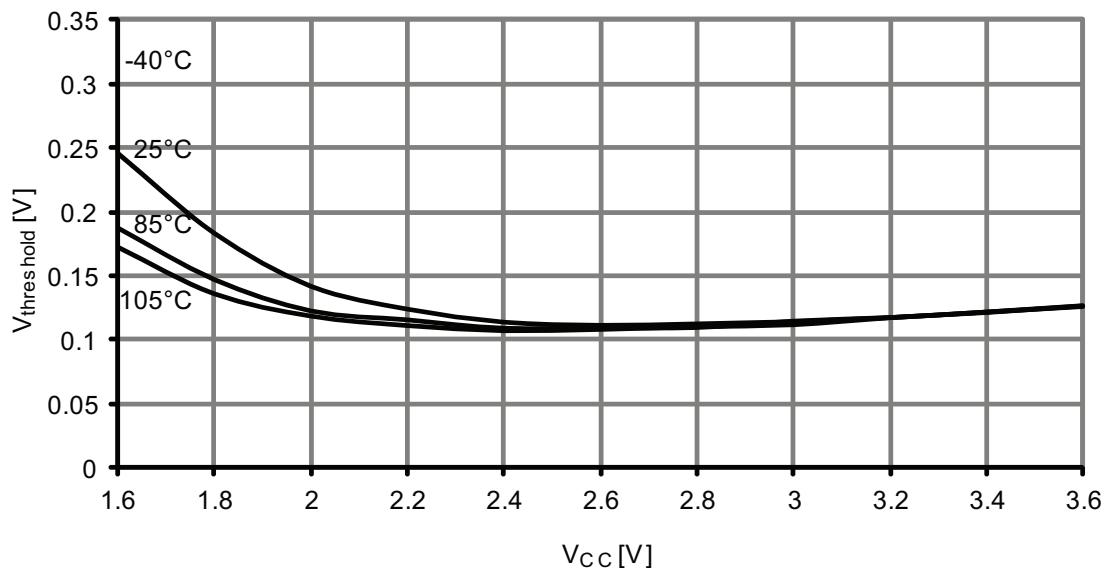


Figure 37-209. Offset error vs. V_{REF} .

$T = 25^\circ\text{C}$, $V_{CC} = 3.6\text{V}$, ADC sampling speed = 500ksps.

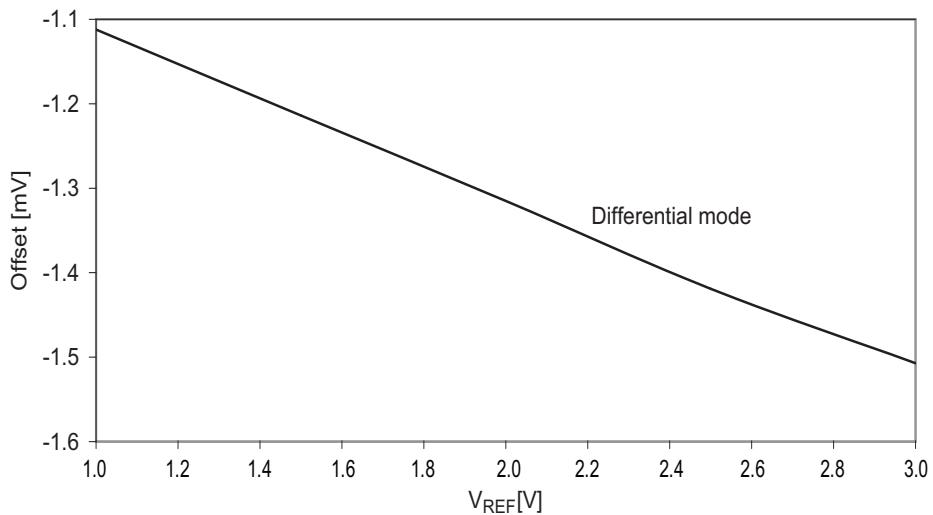


Figure 37-210. Gain error vs. temperature.

$V_{CC} = 2.7\text{V}$, V_{REF} = external 1.0V .

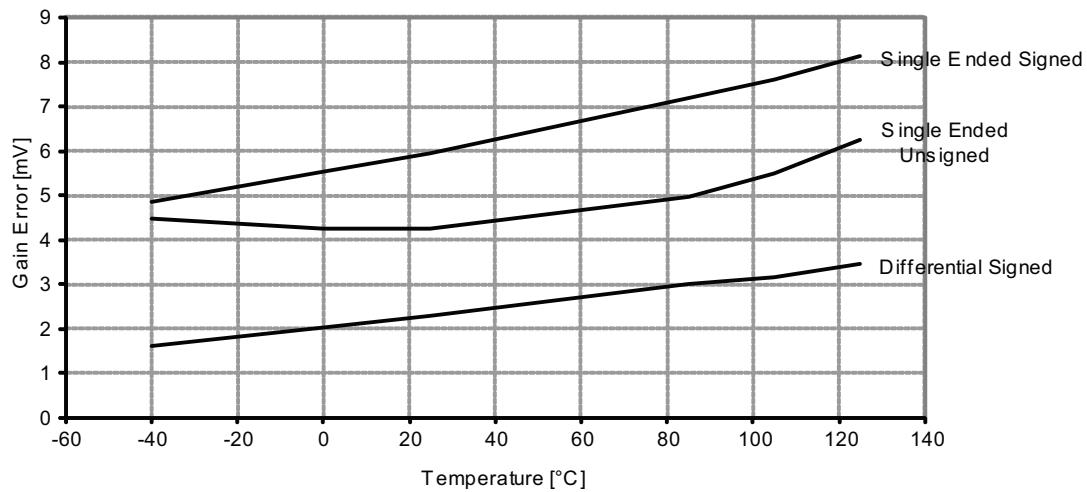
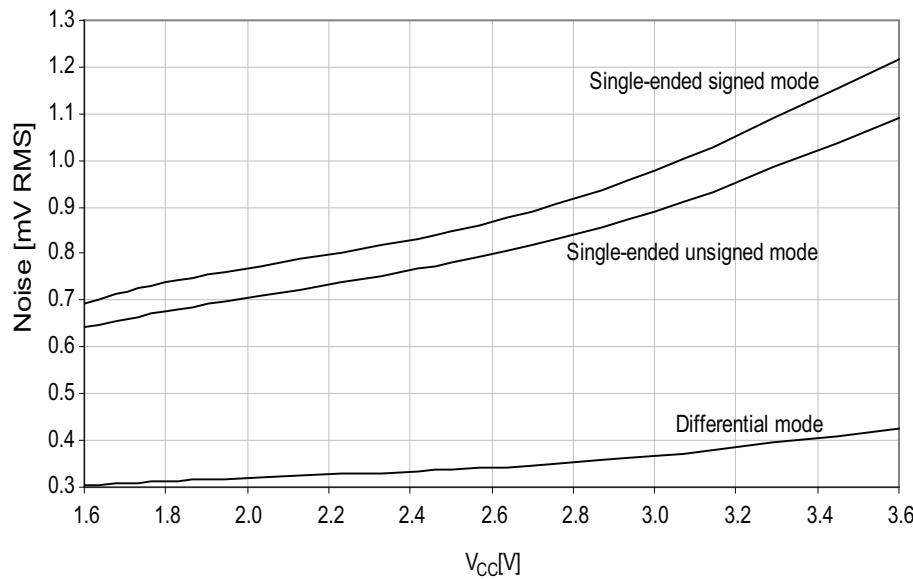


Figure 37-213. Noise vs. V_{CC} .

$T = 25^\circ\text{C}$, $V_{REF} = \text{external } 1.0\text{V}$, ADC sampling speed = 500ksps.



37.3.4 DAC Characteristics

Figure 37-214. DAC INL error vs. V_{REF} .

$V_{CC} = 3.6\text{V}$.

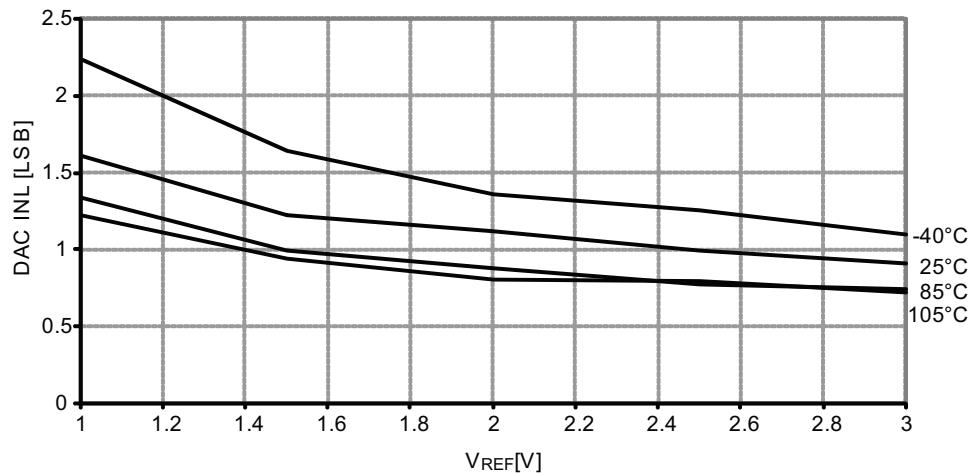


Figure 37-229. Reset pin pull-up resistor current vs. reset pin voltage.

$V_{CC} = 3.0V$.

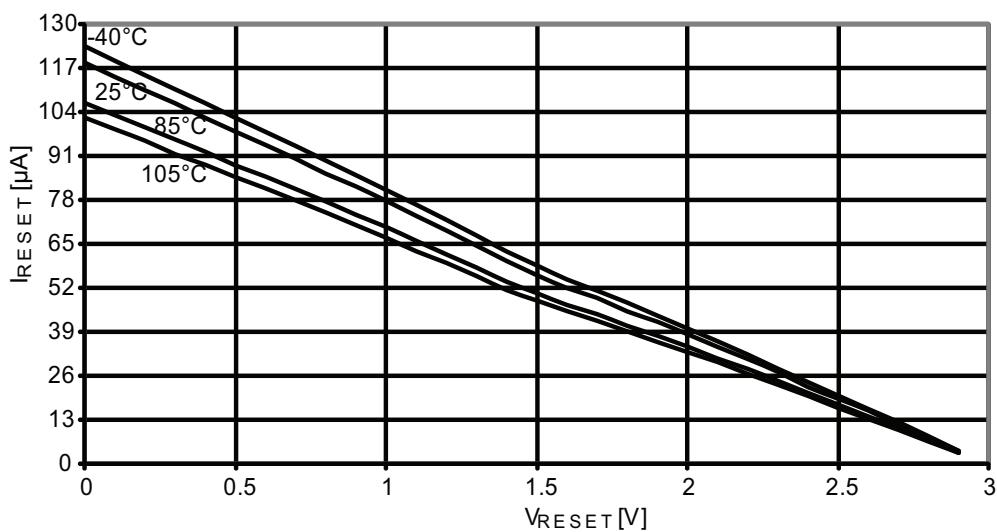


Figure 37-230. Reset pin pull-up resistor current vs. reset pin voltage.

$V_{CC} = 3.3V$.

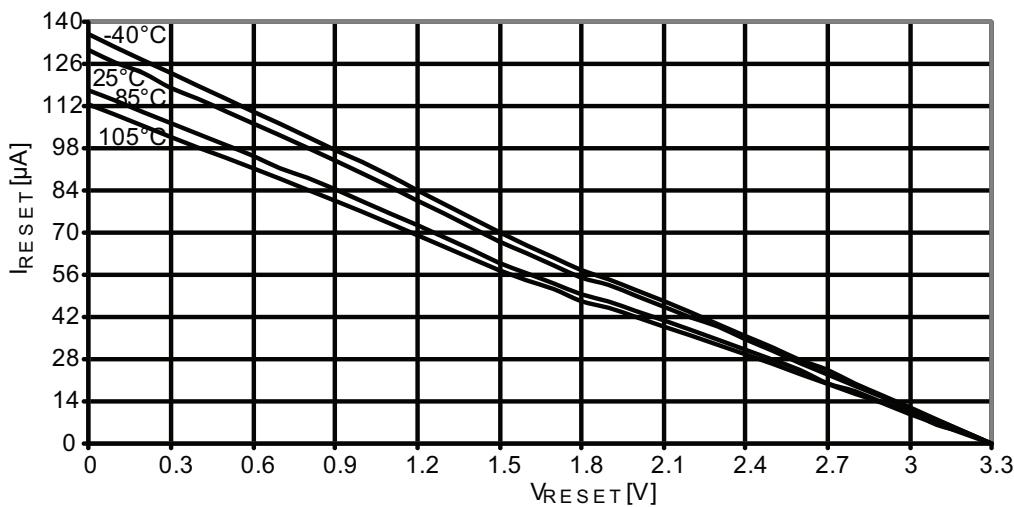


Figure 37-314. Reset pin input threshold voltage vs. V_{CC} .

V_{IH} - Reset pin read as "1".

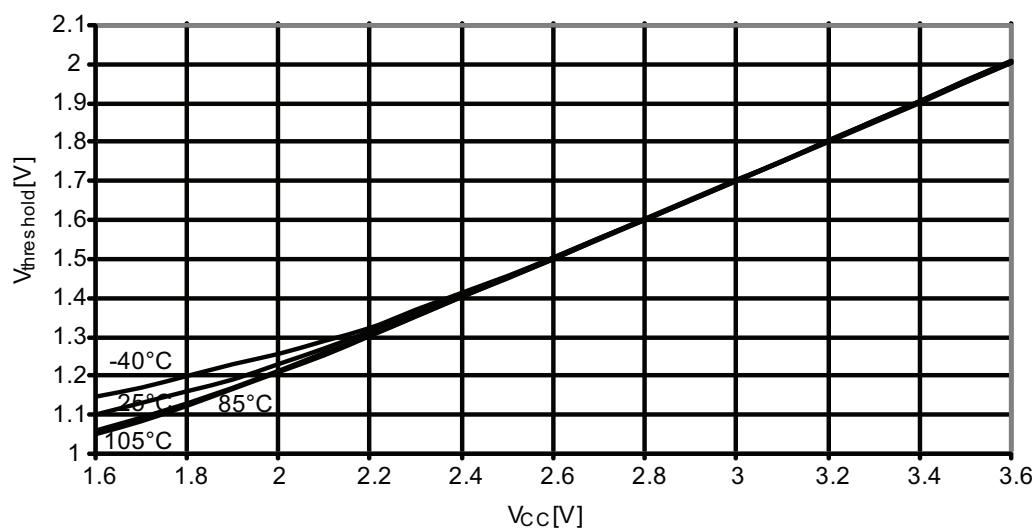


Figure 37-315. Reset pin input threshold voltage vs. V_{CC} .

V_{IL} - Reset pin read as "0".

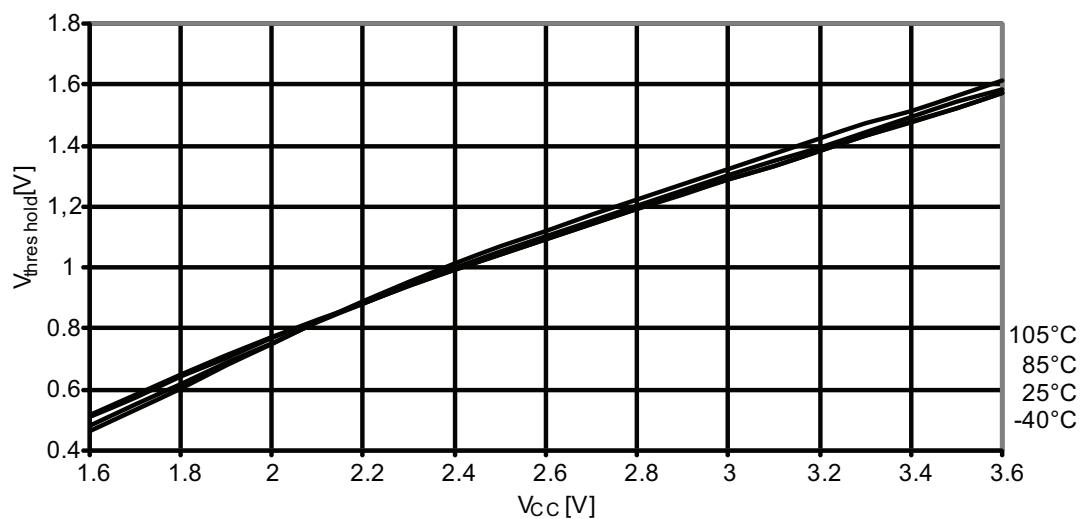


Table of Contents

Features	1
1. Ordering Information	3
2. Pinout/Block Diagram	5
3. Overview	6
3.1 Block Diagram	7
4. Resources	8
4.1 Recommended reading	8
5. Capacitive touch sensing	8
6. AVR CPU	9
6.1 Features	9
6.2 Overview	9
6.3 Architectural Overview	9
6.4 ALU - Arithmetic Logic Unit	11
6.5 Program Flow	11
6.6 Status Register	11
6.7 Stack and Stack Pointer	12
6.8 Register File	12
7. Memories	13
7.1 Features	13
7.2 Overview	13
7.3 Flash Program Memory	14
7.4 Fuses and Lock bits	15
7.5 Data Memory	15
7.6 EEPROM	16
7.7 I/O Memory	16
7.8 Data Memory and Bus Arbitration	17
7.9 Memory Timing	17
7.10 Device ID and Revision	17
7.11 JTAG Disable	17
7.12 I/O Memory Protection	17
7.13 Flash and EEPROM Page Size	17
8. DMAC – Direct Memory Access Controller	19
8.1 Features	19
8.2 Overview	19
9. Event System	20
9.1 Features	20
9.2 Overview	20
10. System Clock and Clock options	22
10.1 Features	22
10.2 Overview	22
10.3 Clock Sources	23